


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/19/11680	
1.3 Title of PCN	New Molding Compound in TO92 package to replace SAMSUNG SDI under termination phase.	
1.4 Product Category	See Products List	
1.5 Issue date	2019-07-22	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Andrea Mario ONETTI
2.1.2 Marketing Manager	Simone FERRI
2.1.3 Quality Manager	Michele CALDERONI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	ASE WEIHAI - CHINA

4. Description of change

	Old	New
4.1 Description	Molding Compound: SAMSUNG EMC type SG-8100G	Molding Compound: EMC GR30HT (Hysol Huawei) as first choice. In meantime, It is under evaluation to consider and qualify a 2nd source as back up (to update reliability results once available)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	As anticipated by PCI No. CRP/19/11478, issued by ST CORPORATE, due to discontinuation of SAMSUNG SDI mold compound, the present notification is to announce the replacement of current molding compound SAMSUNG EMC Type SG-8100G for TO92 package, assembled in ASE WEIHAI plant, with EMC GR30HT (Hysol Huawei) as first choice.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	New Dedicated FGs
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7. Timing / schedule

7.1 Date of qualification results	2019-06-11
7.2 Intended start of delivery	2019-10-14
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
11680 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
LM335Z	LM335Z	

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Public Products List

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PCN Title : New Molding Compound in TO92 package to replace SAMSUNG SDI under termination phase.

PCN Reference : AMS/19/11680

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

LM135Z	LM335AZ	LM335AZT
LM235Z	LM335Z	



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